molex
one company > a world of innovation

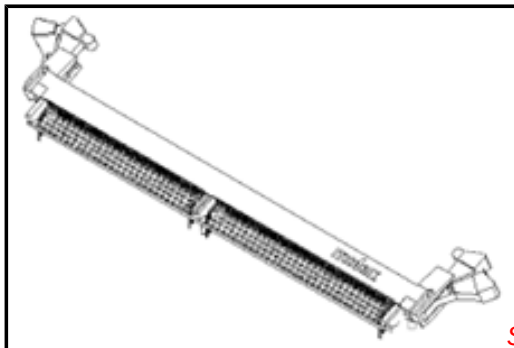
This document was generated on 04/13/2010

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number: 0878030152

Status: Active

Description: 1.00mm (.039") Pitch DDR2 DIMM Socket, Through Hole, 25° Angle, 0.76µm (30µ") Gold (Au), 4.00mm (0.157") Soldertail, 240 Circuits, Lead free



Series image - Reference only

Documents:

3D Model
Drawing (PDF)
Product Specification PS-87803-003 (PDF)
RoHS Certificate of Compliance (PDF)

General

Product Family	Memory Module Sockets
Series	87803
Comments	<LI>No Lubricant at the Contact|<LI>Latches in Off-White Color
Component Type	Socket
JEDEC Outline	MO-237
Product Name	DDR2 DIMM

Physical

Circuits (Loaded)	240
Color - Resin	Black, Natural
Durability (mating cycles max)	25
Entry Angle	25° Angle
Keying to Mating Part	Yes
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
PC Tail Length (in)	0.157 In
PC Tail Length (mm)	4.00 mm
PCB Locator	Yes
PCB Retention	Yes
PCB Thickness Recommended (in)	0.125 In
PCB Thickness Recommended (mm)	3.18 mm
Packaging Type	Tray
Pitch - Mating Interface (in)	0.039 In
Pitch - Mating Interface (mm)	1.00 mm
Plating min: Mating (µin)	30
Plating min: Mating (µm)	0.76
Plating min: Termination (µin)	100
Plating min: Termination (µm)	2.54
Temperature Range - Operating	-55°C to +85°C
Termination Interface: Style	Through Hole

Electrical

Current - Maximum per Contact	0.5A
Voltage - Maximum	30V AC (RMS)/DC
Voltage Key	1.8V, Center

Material Info

Reference - Drawing Numbers

Product Specification	PS-87803-003
Sales Drawing	SD-87803-010

EU RoHS
ELV and RoHS Compliant
REACH SVHC
Contains SVHC: No
Halogen-Free Status
Not Reviewed

China RoHS

Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, click here

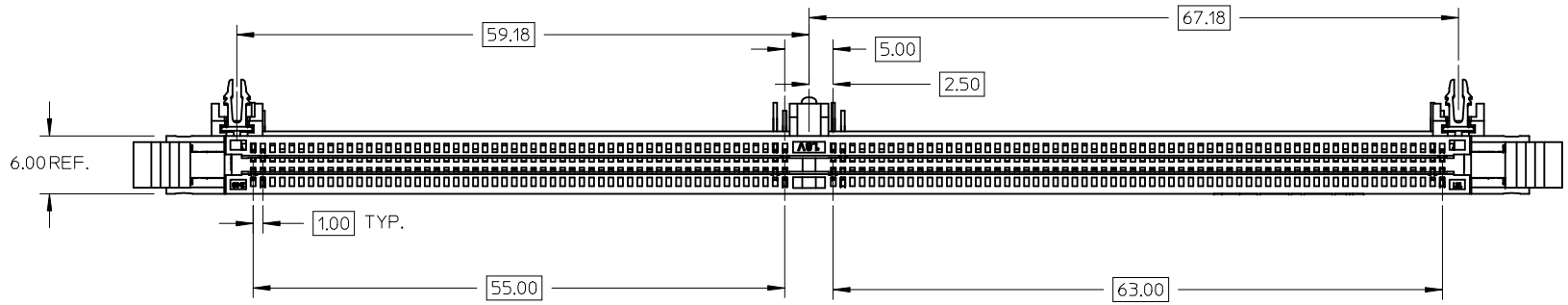
Please visit the Contact Us section for any non-product compliance questions.

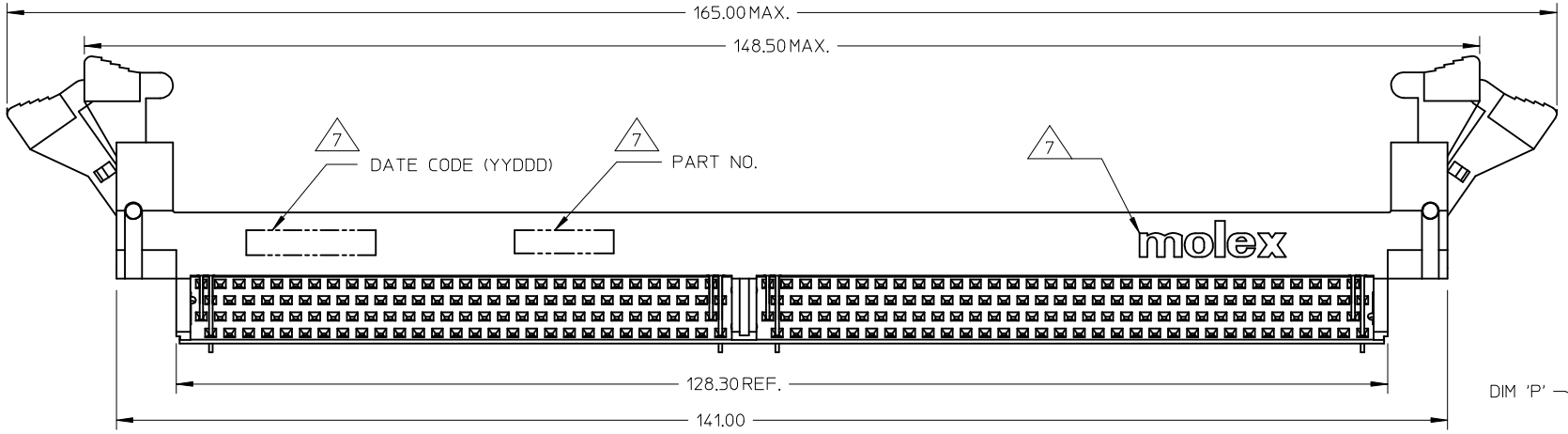
Search Parts in this Series
87803Series

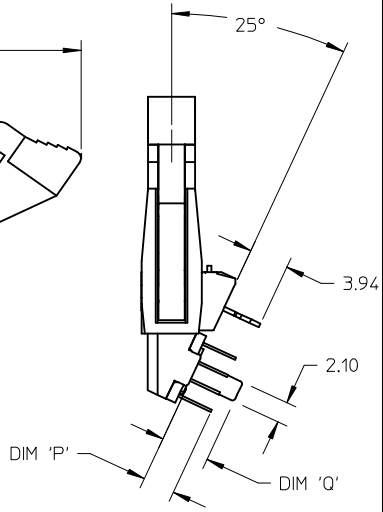
Mates With
JEDEC standard 1.27mm modules

This document was generated on 04/13/2010

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION







NOTES:

1. MATERIALS : HOUSING AND BASEPLATE
   - LCP, GLASS FILLED, UL 94V-0, BLACK
   LATCH
   - HIGH TEMP. NYLON, GLASS FILLED, UL 94-0, NATURAL (OFF WHITE)
   TERMINALS AND FORKLOCK - COPPER ALLOY
2. PLATING : CONTACT AREA - SEE TABLE IN SHEET 5
   SOLDERTAIL - SEE TABLE IN SHEET 5
3. REFER TO PRODUCT SPECIFICATION, PS-87803-003 FOR PERFORMANCE SPECIFICATIONS.
4. CARD SLOTS ACCEPTS 1.27±0.10 MM MODULE THICKNESS. (MEASURED OVER PC PADS)
5. RECOMMENDED MODULE CARD LAYOUT SHALL BE AS PER JEDEC MO-237.
6. PRODUCT IS PACKED IN TRAY.
7. MOLEX LOGO, DATE CODE AND PART NUMBER INDICATED ON HOUSING.
8. CONTACT MOLEX FOR AVAILABILITY OF PRODUCT OPTIONS.

ADDED OPTION
EC NO: S2009-0629 2009/03/27
DRWN:CCTEH 2009/03/27
CH'KD:CGTAN 2009/03/27
APPR:SHLEN1 2009/03/27
DESCRIPTION
REV
B1

QUALITY SYMBOLS
▼=0
Ⓒ▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.25	± ---
1 PLACE	± ---	± ---
ANGULAR ± 5 °		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: NTS
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

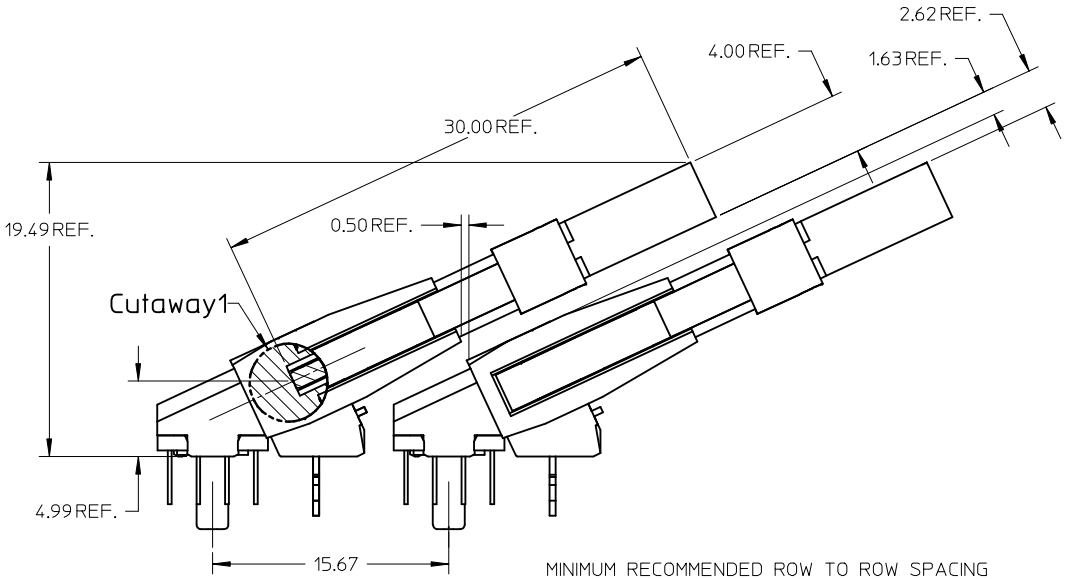
DRAWN BY	MLONG
DATE	2004/03/25
CHECKED BY	SRRAMESH
DATE	2004/03/26
APPROVED BY	GGLEE
DATE	2004/03/26
MATERIAL NO.	SEE TABLE

TITLE: DDR2 DIMM, 1.00MM PITCH 240 CKTS, 25 DEG.

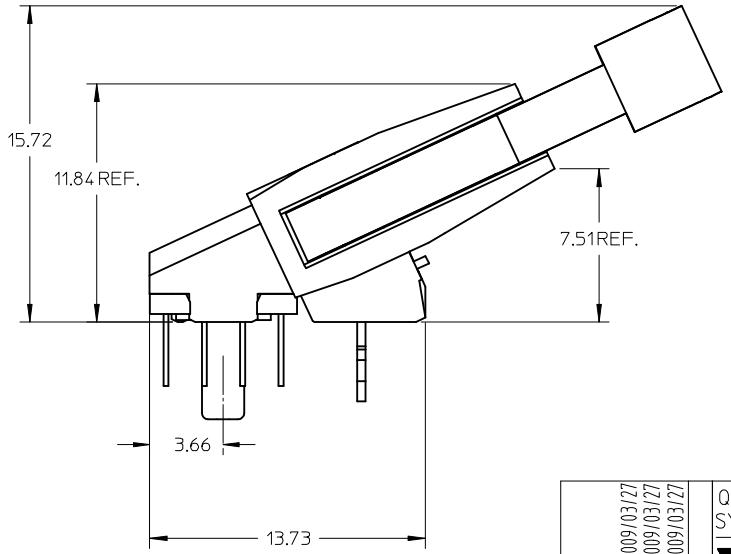
MOLEX INCORPORATED

DOCUMENT NO.: SD-87803-010
SHEET NO.: 1 OF 5
SIZE: A3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION



MINIMUM RECOMMENDED ROW TO ROW SPACING
WHEN USING A 4.00MM THICK
MODULE (TYPICAL TSOP PACKAGING)



ADDED OPTION	2009/03/27	DESCRIPTION	REV
EC NO: S2009-0629	2009/03/27		
DRWN:CCTEH	2009/03/27		
CH'KD:CGTAN			
APPR:SHLEN1			
B1			

QUALITY SYMBOLS
▼=0
Ⓒ=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.25	± ---
1 PLACE	± ---	± ---
ANGULAR ± 5 °		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	SCALE	DESIGN UNITS
MM ONLY	NTS	METRIC

THIRD ANGLE PROJECTION

DRAWN BY	MLONG
DATE	2004/03/25
CHECKED BY	SRRAMESH
DATE	2004/03/26
APPROVED BY	GGLEE
DATE	2004/03/26

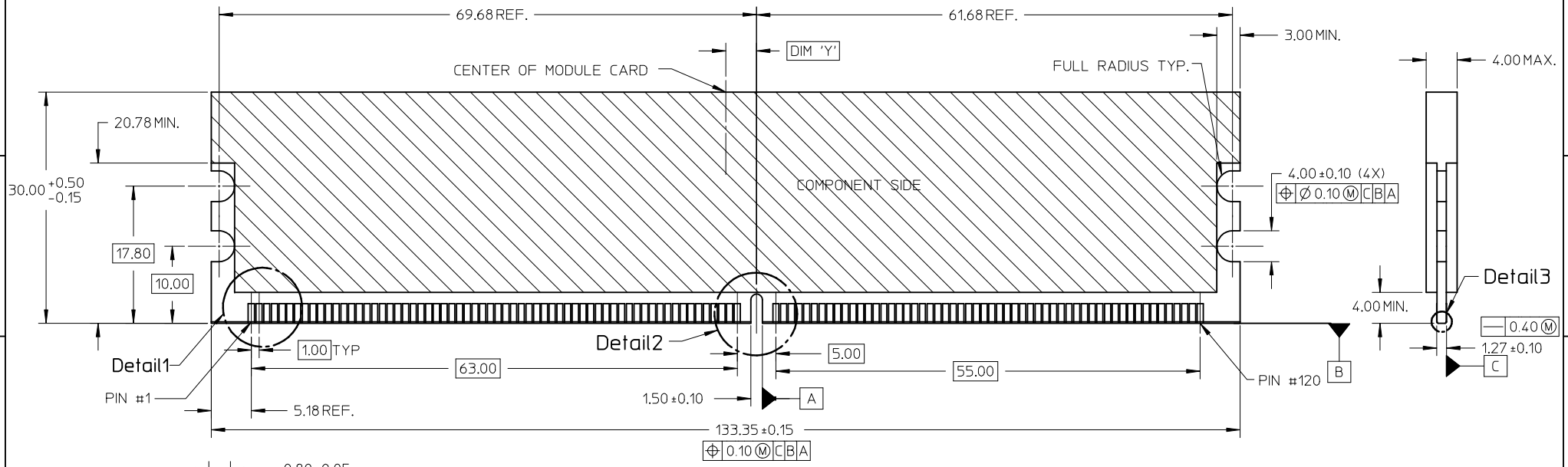
TITLE: DDR2 DIMM, 1.00MM PITCH
240 CKTS, 25 DEG.

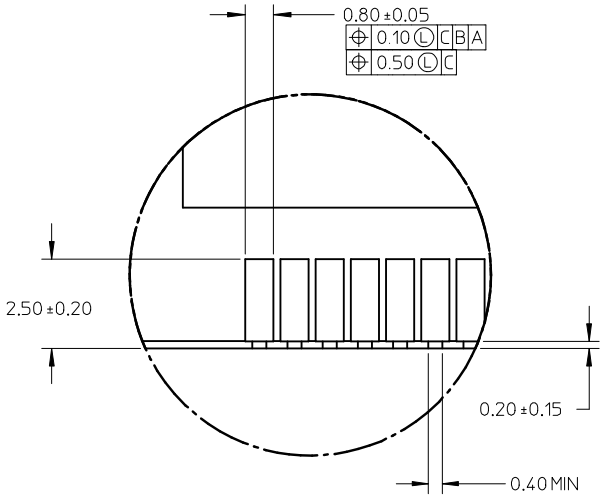
molex MOLEX INCORPORATED

MATERIAL NO.	DOCUMENT NO.	SHEET NO.
SEE TABLE	SD-87803-010	2 OF 5

SIZE A3

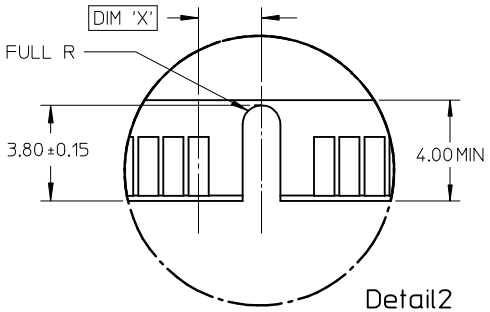
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION



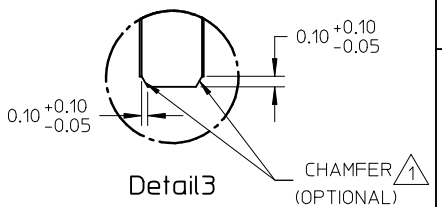


Detail1

RECOMMENDED MODULE LAYOUT



Detail2



Detail3

KEY LOCATION	VOLTAGE	DIM 'X'	DIM 'Y'
CENTER	1.8V	2.50	4.00

NOTES :
1. MODULE CARD USED IN PRODUCT TESTING ARE CHAMFERED.

ADDED OPTION
EC NO: S2009-0629
DRWN:CCTEH 2009/03/27
CHKD:CGTAN 2009/03/27
APPR:SHLEN 2009/03/27
DESCRIPTION
B1
REV

QUALITY SYMBOLS
▼=0
Ⓒ=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.25	± ---
1 PLACE	± ---	± ---
ANGULAR ± 5 °		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: NTS
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

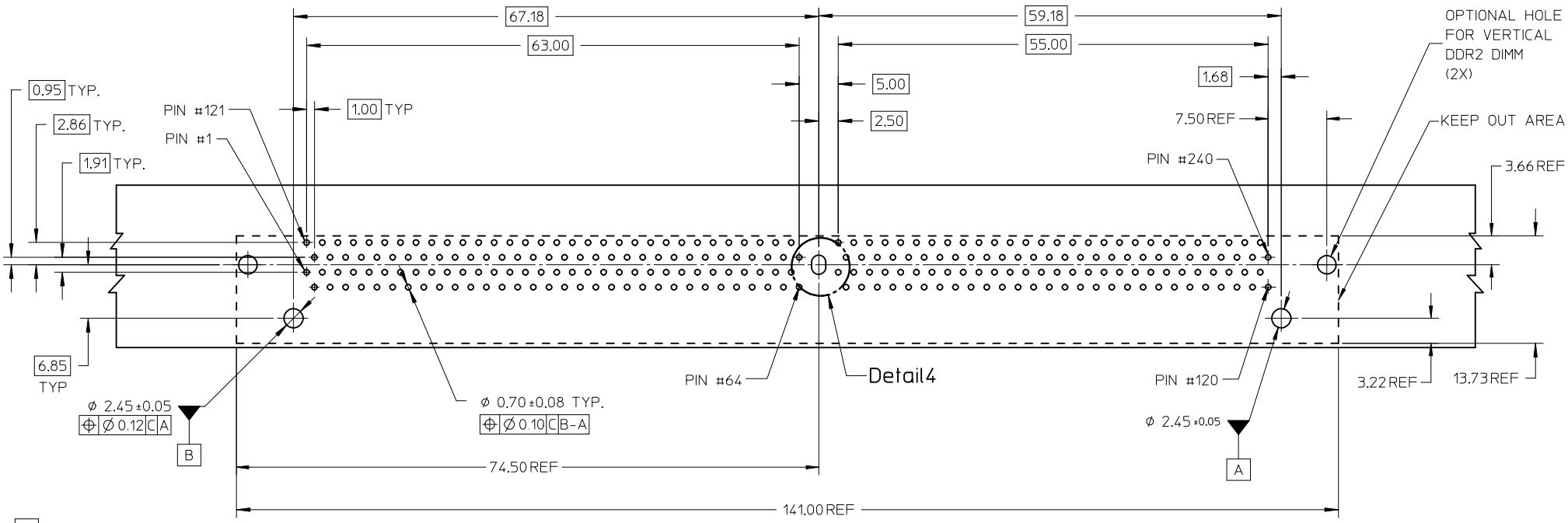
		DATE
DRAWN BY	MLONG	2004/03/25
CHECKED BY	SRRAMESH	2004/03/26
APPROVED BY	GGLEE	2004/03/26

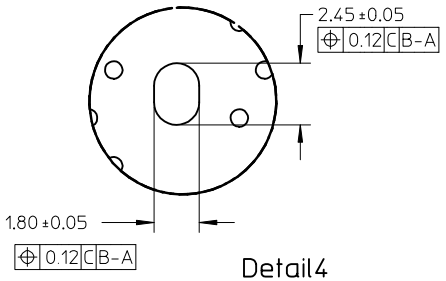
TITLE: DDR2 DIMM, 1.00MM PITCH 240 CKTS, 25 DEG.

MOLEX INCORPORATED

MATERIAL NO.: SEE TABLE
DOCUMENT NO.: SD-87803-010
SHEET NO.: 3 OF 5
SIZE: A3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION





Detail4

ADDED OPTION
EC NO: S2009-0629 2009/03/27
DRWN:CCTEH 2009/03/27
CHKD:CGTAN 2009/03/27
APPR:SHLEN1 2009/03/27
DESCRIPTION
REV
B1

QUALITY SYMBOLS
▼=0
Ⓒ=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.25	± ---
1 PLACE	± ---	± ---
ANGULAR ± 5 °		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: NTS
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

		DATE
DRAWN BY	MLONG	2004/03/25
CHECKED BY	SRRAMESH	2004/03/26
APPROVED BY	GGLEE	2004/03/26

TITLE: DDR2 DIMM, 1.00MM PITCH 240 CKTS, 25 DEG.

MOLEX INCORPORATED

MATERIAL NO.: SEE TABLE
DOCUMENT NO.: SD-87803-010
SHEET NO.: 4 OF 5
SIZE: A3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

PART NO.	VOLTAGE KEY	DIM 'P'	DIM 'Q'	RECOMMENDED PCB THICKNESS	CONTACT AREA PLATING	SOLDERTAIL PLATING	LUBRICATION
87803-0002	1.8V	2.79	3.18	1.57	0.38uM/ 15u" GOLD OVER 1.27uM/ 50u" MIN NICKEL	2.54uM/ 100u" MIN. TIN (MATTE) OVER 1.27uM/ 50u" MIN NICKEL	NO
87803-0022							YES
87803-0012		3.18	4.83	2.36			NO
87803-0032							YES
87803-0052		4.00		3.18			NO
87803-0062							YES
87803-0102		2.79	3.18	1.57	0.76uM/ 30u" GOLD OVER 1.27uM/ 50u" MIN NICKEL		NO
87803-0122							YES
87803-0112		3.18	4.83	2.36			NO
87803-0132							YES
87803-0152		4.00		3.18			NO
87803-0162							YES

ADDED OPTION
EC NO: S2009-0629 2009/03/27
DRWN:CCTEH 2009/03/27
CH'KD:CGTAN 2009/03/27
APPR:SHLEN1 2009/03/27
DESCRIPTION
REV
B1

QUALITY SYMBOLS
▼=0
Ⓒ▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.25	± ---
1 PLACE	± ---	± ---
ANGULAR ± 5 °		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: NTS
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: MLONG DATE: 2004/03/25
CHECKED BY: SRRAMESH DATE: 2004/03/26
APPROVED BY: GGLEE DATE: 2004/03/26

TITLE: DDR2 DIMM, 1.00MM PITCH 240 CKTS, 25 DEG.

MOLEX INCORPORATED

MATERIAL NO.: SEE TABLE
DOCUMENT NO.: SD-87803-010
SHEET NO.: 5 OF 5
SIZE: A3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION